

XP-002402691

WPI / Thomson

AN - 1999-148753 [13]
AP - JP19970164698 19970620
CPY - HITB
DC - A26 A85 G02 L03
- V04
DCR - [1] 107016 DIS; 129411 DIS; 129524 USE; 400 DIS; 780 DIS; 9521 DIS
DR - 1363-U
DW - 199913
IC - C09D5/04; C08G18/34; C08G18/69; C08G73/10; C08L79/08; C09D179/08;
C09D5/34; C09D7/12; H05K3/28; H05K3/46
IN - KAWAKAMI H; NISHIZAWA H; SAKATA T; SUZUKI K
LNKA- 1999-044111; 1999-108636
MC - A05-F A05-J01B A12-E01 G02-A05B G03-B02E L03-D05A
- V04-R03E V04-R05A
PA - (HITB) HITACHI CHEM CO LTD
PN - JP11012499 A 19990119 DW199913
PR - JP19970164698 19970620
XIC - C09D-005/04; C08G-018/34; C08G-018/69; C08G-073/10; C08L-079/08;
C09D-179/08; C09D-005/34; C09D-007/12; H05K-003/28; H05K-003/46
AB - A moisture heat-resistant modified polyamide-imide resin paste with
thixotropic properties comprises dispersing organic and/or inorganic
fine particles into a modified polyamide- imide resin bearing a
polybutadiene or its hydrogenated prod. backbone. Also claimed are
electronic parts with an interlayer insulator, passivation layer,
solder resist layer or an adhesive layer of the paste.
- ADVANTAGE :
The modified polyamide-imide resin pastes have thixotropic properties
suitable for screen printing, excellent moisture heat resistance,
continuous printability, screen stencil life-elongating properties,
pattern formability by screen printing, flexibility, adhesion,
workability, storage stability and low temp. curing properties and low
warp, modulus and moisture absorption and are economical. Interlayer
insulators, passivation layers, solder resist layers and adhesive
layers of electronic parts such as wiring boards and semiconductor
devices have excellent adhesion, flexibility and resolution and low
modulus.
INW - KAWAKAMI H; NISHIZAWA H; SAKATA T; SUZUKI K
IW - MOIST HEAT RESISTANCE MODIFIED POLYAMIDE IMIDE RESIN PASTE COMPRISE
DISPERSE ORGANIC INORGANIC FINE PARTICLE BEARING POLYBUTADIENE
HYDROGENATION PRODUCT BACKBONE
IWW - MOIST HEAT RESISTANCE MODIFIED POLYAMIDE IMIDE RESIN PASTE COMPRISE
DISPERSE ORGANIC INORGANIC FINE PARTICLE BEARING POLYBUTADIENE
HYDROGENATION PRODUCT BACKBONE
NC - 1
NPN - 1
OPD - 1997-06-20
PAW - (HITB) HITACHI CHEM CO LTD
PD - 1999-01-19
TI - Moisture heat-resistant modified polyamide-imide resin pastes -
comprises dispersing organic and/or inorganic fine particles into a
modified polyamide- imide resin bearing a polybutadiene or its

hydrogenated product backbone

A01 - [001] 018; G1843 D01 F73 G1912 G1854 G1843 D11 D10 D19 D18 D31 D50 D76
D89 D18; R00735 G1887 G1854 G1843 D01 D11 D19 D18 D32 D50 D76 D93
F73 9521; E30 D65 F39; R01363 G1423 G1398 D24 D01 D24 D22 D32 D42
D50 D60 D65 D77 D89 F36 F35 F39 E30 E31 129524; G1365 G1343 G1310
G4024 D01 D60 F37 F35 E00 E28 D11 D10 D12 D55 D51 D56 D59 D50 D95 D58
H0204; H0293; P0055; P0077; P0771 P0635 P1081 H0260 F70 F72 D01; S9999
S1627 S1605; L9999 L2528 L2506; L9999 L2664 L2506; L9999 L2084; L9999
L2028; L9999 L2335; L9999 L2744 L2733; H0033 H0011

- [002] 018; ND01; ND04; B9999 B3509 B3485 B3372; B9999 B4682 B4568;
B9999 B4717 B4706 B4568; B9999 B3689 B3554; Q9999 Q7330; B9999 B4035
B3930 B3838 B3747; B9999 B5301 B5298 B5276; B9999 B3623 B3554; B9999
B3532 B3372; B9999 B4988 B4977 B4740; B9999 B3178; K9665; B9999 B3758
B3747; Q9999 Q7374 Q7330; Q9999 Q7454 Q7330; Q9999 Q7476 Q7330; B9999
B3838 B3747; B9999 B5094 B4977 B4740; Q9999 Q6644; K9483; K9676; K9687
K9676; K9712 K9676; B9999 B3678 B3554; Q9999 Q8684 Q8673 Q8606; B9999
B4397 B4240; K9870 K9847 K9790

- [003] 018; R00644 G2131 D01 D23 D22 D31 D42 D50 D75 D84 F43 780;
R01084 D01 D11 D10 D50 D84 F70 400; A999 A475; A999 A771; K9734

- [004] 018; D00 D01; R01694 D00 F20 O- 6A Si 4A 107016; A999 A726 A691;
A999 A771; S9999 S1456; S9999 S1514 S1456; B9999 B5209 B5185 B4740

A02 - [001] 018; R00806 G0828 G0817 D01 D02 D12 D10 D51 D54 D56 D58 D84
129411; H0000; H0191; M9999 M2062; M9999 M2153; M9999 M2722 M2711;
P0328; P0339